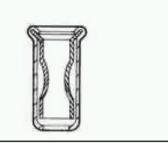
Documentation ♥

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Home > Products > By Type > Socket/Card Products > Product Feature Selector > Product Details

1-332070-4 Product Details



1-332070-4

TE Part Number: 1-332070-4

✓ Active

Add to Part List

Discrete Sockets



Always EU RoHS/ELV Compliant (Statement of Compliance)

Product Highlights:

- Socket
- Mating Pin Dia. Range = .94 1.02
- Socket Length = 3.63 mm
- Sleeve Style = Open Bottom
- Gold Flash over Nickel Sleeve Plating

View all Features | Find Similar Products

Live Product Chat

Quick Links

- Check Pricing & Availability
- Search for Tooling
- Product Feature Selector
- Contact Us About This Product
- Request Samples NEW!

Documentation & Additional Information

Product Drawings:

 MINIATURE SPRING SOCKET ASSEMBLY, SERIES 4 (PDF, English)

Catalog Pages/Data Sheets:

None Available

Product Specifications:

None Available

Application Specifications:

Miniature Spring Socket Contacts (PDF, English)

Instruction Sheets:

None Available

CAD Files: (CAD Format & Compression Information)

- 2D Drawing (DXF, Version AJ2)
- <u>3D Model</u> (IGES, Version AJ2)
- 3D Model (STEP, Version AJ2)

Additional Information:

Product Line Information

Related Products:

Tooling

List all Documents

Product Features (Please use the Product Drawing for all design activity)

Product Type Features:

- Product Type = Socket
- Socket Length (mm [in]) = 3.63 [0.143]
- Sleeve Style = Open Bottom
- Sealant = Without
- Recommended Hole Size (mm [in]) = 1.83 [0.072]

Body Related Features:

- Mating Pin Dia. Range (mm [in]) = 0.94 1.02 [0.037 - 0.040]
- Spring Material = Beryllium Copper

Contact Related Features:

- <u>Sleeve Plating</u> = Gold Flash over Nickel
- Contact Spring Plating = Gold (30)
- <u>Contact Material</u> = Beryllium Copper

Configuration Related Features:

<u>Insertion Method</u> = Hand/Semi-Automatic

Industry Standards:

- Government/Industry Qualification = No.
- RoHS/ELV Compliance = RoHS compliant, ELV compliant
- <u>Lead Free Solder Processes</u> = Wave solder capable to 240°C, Wave solder capable to 260° C, Wave solder capable to 265°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin-in-Paste capable to 245°C, Pinin-Paste capable to 260°C
- RoHS/ELV Compliance History = Always was RoHS compliant

Operation/Application:

Application = Production

Packaging Related Features:

Packaging Method = Loose Piece

Other:

Brand = AMP

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